# Heraeus

## **TSC Series**

## **Applications**

Semiconductor, solar, LED and flat panel display applications.

## Characteristics

High purity quartz solid and hollow material with low bubble content.

#### **TSC Grades**

TSC ingots are made with the highest quality natural quartz powders that have been refined using Heraeus' proprietary purification process.

These high purity powders are then fused using Heraeus' unique flame fusion technique resulting in material with low levels of alkali and very few bubbles and inclusions.

Specializing in "near-net-shape", TSC ingots are available in rectangular, round and hollow shapes and in a wide range of sizes. These near-net-shape ingots help to reduce costs in volume applications. Ingots can be cut and ground or lapped to make blanks in a variety of shapes including rectangular or square plates, discs and rings.



**TSC-3**® is the standard semiconductor grade material, ideal for use in single wafer processing applications such as plasma etch and deposition systems.

**TSC-4** further reduces the risk of contamination by providing a lower Al and alkali content. TSC-4 has been designed for the most demanding semiconductor applications.

#### **Available Dimensions**

The TSC Series is readily available in large sizes of up to 670 x 2200 mm. Larger sizes are available on request, please check for availability.

#### Rectangular Ingots (Length up to 2200 mm)

(mm)	200			
	160			
Thickness	120			
Width (mm)		450	540	670

#### **Hollow Ingots**

	mm
OD	Up to 670
OD tolerance	+4 / -0
Wall thickness	≥ 15

#### **Round Ingots**

	2300					
mu (mu	1900					
Length (mm)	210					
Len	160					
	120					
Diameter (mm)		310	350	420	540	670

Chemical Purity — Typical trace elements and OH content in quartz glass (ppm by weight oxide)													
Elements	Al	Ca	Cr	Cu	Fe	K	Li	Mg	Mn	Na	Ti	Zr	ОН
TSC-3®	15	0.4	< 0.01	< 0.01	0.05	0.2	0.2	< 0.01	< 0.01	0.3	1.1	0.8	170
TSC-4	8	0.7	< 0.01	< 0.01	0.1	0.08	0.04	< 0.01	< 0.01	0.2	1.3	0.7	170

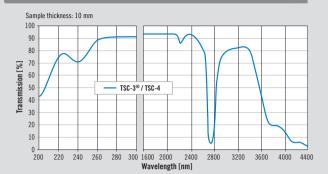
## **Bubbles and Inclusions**

Heraeus' flame fusion process has been developed to ensure TSC materials have much fewer bubbles and inclusions than traditional electrically fused quartz.

#### Table showing typical combined bubble and inclusion counts per ft<sup>3</sup>

Grade	Bubble & Inclusion Diameter (mm)						
	< 0.3 0.3 ~ 0.5 0.5 ~ 1.0 >						
TSC-3® & TSC-4	Not Specified	7	0	0			

## Typical Transmission Spectrum (including Fresnel reflection losses)



Electric Data TSC-3® / TSC-4

## Technical Properties TSC-3®/TSC-4

Mechanical Data	
Density (g/cm³)	2.2
Mohs Hardness	5.5 6.5
Micro Hardness (N/mm²)	8600 9800
Knoop Hardness (N/mm²)	5800 6100
Modulus of elasticity at 20 °C (N/mm²)	7.3 x 10 <sup>4</sup>
Modulus of torsion (N/mm²)	3.0 x 10 <sup>4</sup>
Poisson's ratio	0.16
Compressive strength (approx.) (N/mm²)	1110
Tensile strength (approx.) (N/mm²)	50
Bending strength (approx.) (N/mm²)	65
Torsional strength (approx.) (N/mm²)	30
Sound velocity (m/s)	5700
Thermal Data	
Softening temperature (°C)	1730
Annealing temperature (°C)	1200
Strain temperature (°C)	1080
$\overline{\text{Max. working temperature} - \text{continuous (°C)}}$	1050
Max. working temperature – short term (°C)	1350

Mean specific heat (J/kg*K)	
0 100 °C	772
0 500 °C	964
0 900 °C	1052
Heat conductivity (W/m*K)	
20 °C	1.38
100°C	1.47
200°C	1.55
300°C	1.67
400°C	1.84
950 °C	2.68
Mean expansion coefficient (K-1)	
0 100 °C	5.1 x 10 <sup>-7</sup>
0 200 °C	5.8 x 10 <sup>-7</sup>
0 300 °C	5.9 x 10 <sup>-7</sup>
0 600 °C	5.4 x 10 <sup>-7</sup>
0 900 °C	4.8 x 10 <sup>-7</sup>

Electri	ical resistivity (Ω*m)	)
20°C		1016
400°C		1010
800°C		6.3 x 10 <sup>6</sup>
1200°	С	1.3 x 10 <sup>3</sup>
Dielect	tric strength (kV/mm)	[sample thickness ≥ 5 mm]
20°C		25 40
500°C		4 5
Dielect	tric loss angle (tg δ)	
1 kHz		5.0 x 10 <sup>-4</sup>
1 MHz		1.0 x 10 <sup>-4</sup>
3 x 10 <sup>1</sup>	<sup>0</sup> Hz	4.0 x 10 <sup>-4</sup>
Dielect	tric constant $(oldsymbol{arepsilon})$	
20°C	0 10 <sup>6</sup> Hz	3.70
23°C	9 10 <sup>8</sup> Hz	3.77
23°C	3 10 <sup>10</sup> Hz	3.81

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